

Features

- **1A Output Current**
- **Support 4 AA alkaline, NiCd or NiMH batteries**
- **Wide 3.5V~7.2V Input Voltage**
- **Fixed 1.5MHz Switching Frequency**
- **Low Dropout Operating at 100% duty cycle**
- **Low 25mA Quiescent Current**
- **Integrate Synchronous Rectifier**
- **0.6V Low Reference Voltage**
- **<0.5mA Input Current during Shutdown**
- **Current-Mode Operation with Internal Compensation**
 - Stable with Ceramic Output Capacitors
 - Fast Line Transient Response
- **Short-Circuit Protection**
- **Over-Temperature Protection with Hysteresis**
- **Available in TDFN2x2-8 Package**
- **Lead Free and Green Devices Available (RoHS Compliant)**

Applications

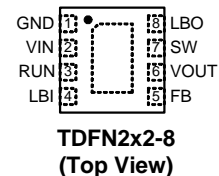
- **E-Book**
- **Toy**
- **Portable Instrument**

General Description

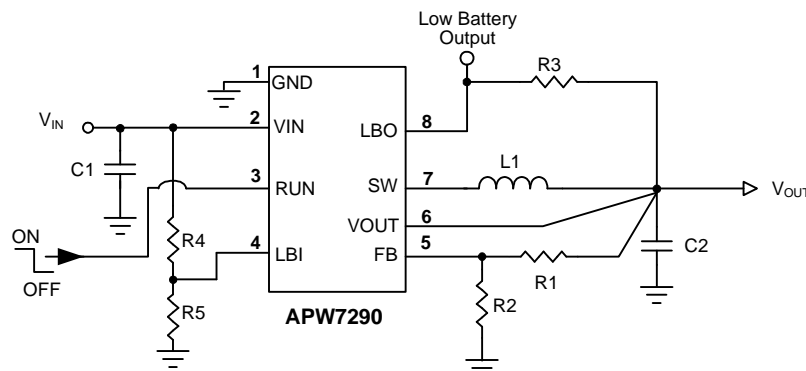
The APW7290 is a high efficiency monolithic synchronous buck regulator. APW7290 operates with a constant 1.5MHz switching frequency and using the inductor current as a controlled quantity in the current mode architecture. The 3.5V to 7.2V input voltage range makes the APW7290 ideally suited for single Li-Ion battery powered applications. 100% duty cycle provides low dropout operation, extending battery life in portable electrical devices. The internally fixed 1.5MHz operating frequency allows the use of small surface mount inductors and capacitors. The synchronous switches included inside increase the efficiency and eliminate the need for an external Schottky diode.

The APW7290 is available in TDFN2x2-8 package.

Pin Configuration

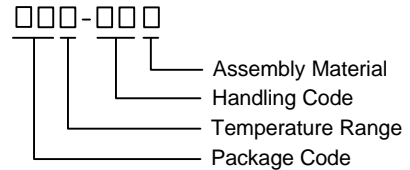


Simplified Application Circuit



ANPEC reserves the right to make changes to improve reliability or manufacturability without notice, and advise customers to obtain the latest version of relevant information to verify before placing orders.

Ordering and Marking Information

<p>APW7290</p>  <p> Assembly Material Handling Code Temperature Range Package Code </p>	<p> Package Code QB : TDFN2x2-8 Operating Ambient Temperature Range I : -40 to 85 °C Handling Code TR : Tape & Reel Assembly Material G : Halogen and Lead Free Device L : Lead Free Device </p>		
<p>APW7290 QB :</p> <table border="1" style="display: inline-table; margin-left: 20px;"> <tr> <td style="padding: 2px;">W90</td> </tr> <tr> <td style="text-align: center;">● X</td> </tr> </table>	W90	● X	<p>X - Date Code</p>
W90			
● X			

Note: ANPEC lead-free products contain molding compounds/die attach materials and 100% matte tin plate termination finish; which are fully compliant with RoHS. ANPEC lead-free products meet or exceed the lead-free requirements of IPC/JEDEC J-STD-020D for MSL classification at lead-free peak reflow temperature. ANPEC defines "Green" to mean lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

Absolute Maximum Ratings (Note 1)

Symbol	Parameter	Rating	Unit
V_{IN}	Input Bias Supply Voltage (VIN to GND)	-0.3 ~ 8	V
V_{SW}	SW to GND Voltage	-0.3 ~ $V_{IN}+0.3$	V
$V_{I/O}$	LBO and RUN to GND Voltage	-0.3 ~ 8	V
	LBI and FB to GND Voltage	-0.3 ~ 3.3	V
P_D	Power Dissipation	Internally Limited	W
	Maximum Junction Temperature	150	°C
T_{STG}	Storage Temperature	-65 ~ 150	°C
T_{SDR}	Maximum Lead Soldering Temperature (10 Seconds)	260	°C

Note1: Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Thermal Characteristics

Symbol	Parameter	Typical Value	Unit
θ_{JA}	Junction-to-Ambient Resistance in Free Air ^(Note 2)	TDFN2x2-8 165	°C/W
θ_{JC}	Junction-to-Case Resistance	TDFN2x2-8 20	°C/W

Note 2: θ_{JA} is measured with the component mounted on a high effective thermal conductivity test board in free air.

Recommended Operating Conditions (Note 3)

Symbol	Parameter	Range	Unit
V_{IN}	Input Bias Supply Voltage (VIN to GND)	3.5 ~ 7.2	V
V_{OUT}	Converter Output Voltage	Adj : 0.6 ~ 6 Fixed : 1.8	V
I_{OUT}	Converter Output Current	0 ~ 1	A
L1	Converter Output Inductor	1.0 ~ 10	μ H
C_{IN}	Converter Input Capacitor	4.7 ~	μ F
C_{OUT}	Converter Output Capacitor	4.7 ~	μ F
T_A	Ambient Temperature	-40 ~ 85	$^{\circ}$ C
T_J	Junction Temperature	-40 ~ 125	$^{\circ}$ C

Note 3: Refer to the typical application circuit

Electrical Characteristics

Unless otherwise specified, these specifications apply over $V_{IN}=5V$ and $T_A = -40 \sim 85^{\circ}C$. Typical values are at $T_A=25^{\circ}C$.

Symbol	Parameter	Test Conditions	APW7290			Unit
			Min	Typ	Max	
SUPPLY VOLTAGE AND CURRENT						
V_{IN}	Input Voltage Range		3.5	-	7.2	V
I_{DD}	Quiescent Current	$V_{FB} = 0.66V$	-	25	40	μ A
I_{SD}	Shutdown Input Current	RUN = GND	-	-	0.5	μ A
POWER-ON-RESET (POR) and LOCKOUT VOLTAGE THRESHOLDS						
	UVLO Threshold		3.0	3.2	3.4	V
	UVLO Hysteresis		-	200	-	mV
REFERENCE VOLTAGE						
V_{REF}	Regulated Voltage	$V_{IN}=3.5V\sim 7.2V, T_A = -40\sim 85^{\circ}C,$	0.588	0.6	0.612	V
	Output Voltage Accuracy	$0A < I_{OUT} < 1A$	-2.5	-	+2.5	%
I_{FB}	FB Input Current		-50	-	50	nA
VOUT	Output Voltage	FB=GND, No Load	1.764	1.8	1.836	V
INTERNAL POWER MOSFETS						
F_{SW}	Switching Frequency	$V_{FB} = 0.6V$	1.2	1.5	1.8	MHz
	Fold Back Frequency	$V_{FB} = 0.1V$	-	210	-	KHz
	Fold Back Voltage on FB	V_{FB} Falling	-	0.2	-	V
	Fold Back Hysteresis	V_{FB} Rising	-	120	-	mV
R_{P-FET}	High Side P-FET Switch ON Resistance	$I_{SW}=200mA$	-	0.28	-	Ω
R_{N-FET}	Low Side N-FET Switch ON Resistance	$I_{SW}=200mA$	-	0.25	-	Ω
	Minimum On-Time		-	-	100	ns
	Maximum Duty Cycle		-	-	100	%

Electrical Characteristics

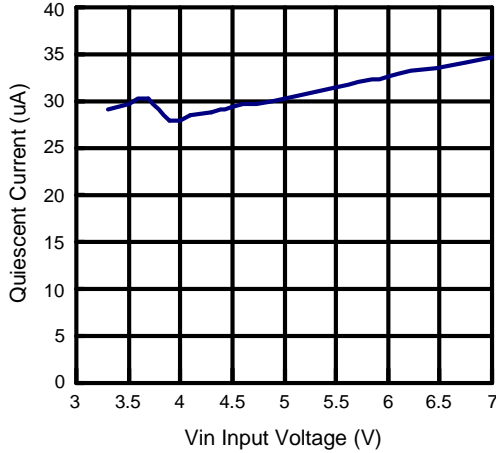
Unless otherwise specified, these specifications apply over $V_{IN}=5V$ and $T_A = -40 \sim 85^\circ C$. Typical values are at $T_A=25^\circ C$.

Symbol	Parameter	Test Conditions	APW7290			Unit
			Min	Typ	Max	
PROTECTION						
I_{LIM}	Maximum Inductor Current Limit	$I_{P-FET}, 3.5V$ $V_{IN} 7.2V$	1.4	1.6	-	A
T_{OTP}	Over-Temperature Protection	T_J Rising	-	150	-	°C
	Over-Temperature Protection Hysteresis	T_J Falling	-	30	-	
START-UP AND SHUTDOWN						
T_{SS}	Soft-start Duration	(Note 4)	-	0.7	-	ms
	RUN Input High Threshold	$V_{IN} = 3.5V \sim 7.2V$	-	-	1	V
	RUN Input Low Threshold	$V_{IN} = 3.5V \sim 7.2V$	0.4	-	-	V
	RUN Leakage Current	$V_{RUN} = 5V, V_{IN} = 5V$	-1	-	1	μA
V_{LBI}	LBI Threshold		0.588	0.6	0.612	V
I_{LBI}	LBI Input Current	$V_{LBI}=0.8V$	-	1	50	nA
	LBI Input Hysteresis		-	10	-	mV
V_{LBO}	LBO Logic Low	$V_{LBI}=3.3V, I_{SINK}=1mA$	-	0.2	0.4	V
I_{LBO}	LBO Off Leakage Current	$V_{LBO}=5.5V, V_{LBI}=0V$	-	0.07	1	μA

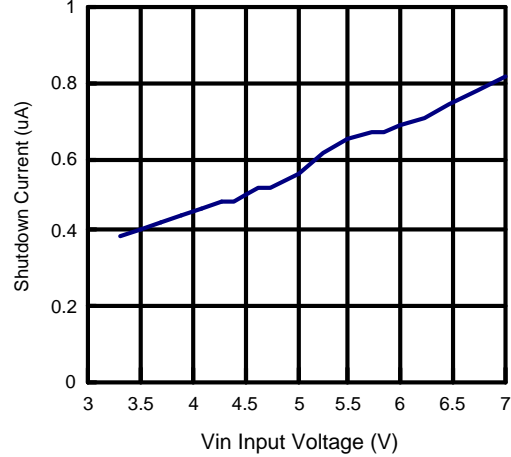
Note 4: Guarantee by design, not production test.

Typical Operating Characteristics

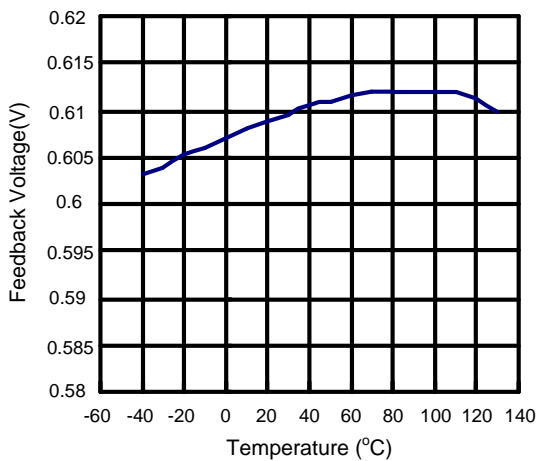
Vin Input Voltage vs. Quiescent Current



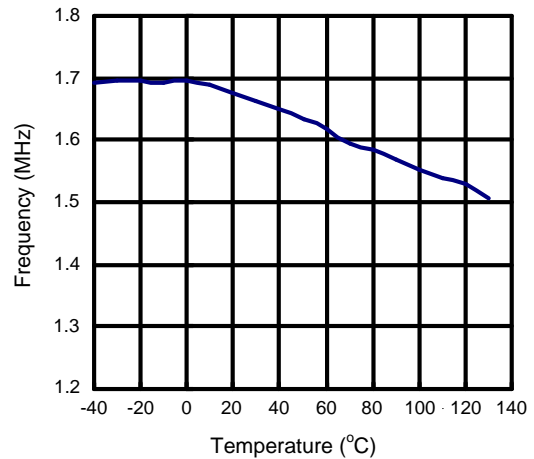
Vin Input Voltage vs. Shutdown Current



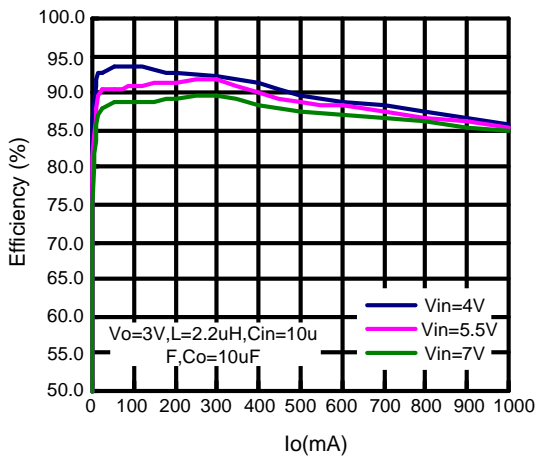
Temperature vs. Feedback Voltage



Temperature vs. Frequency

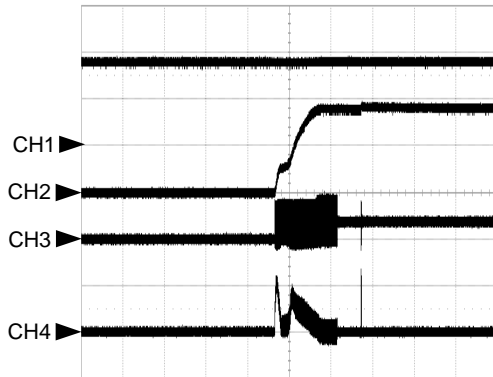


Io vs. Efficiency



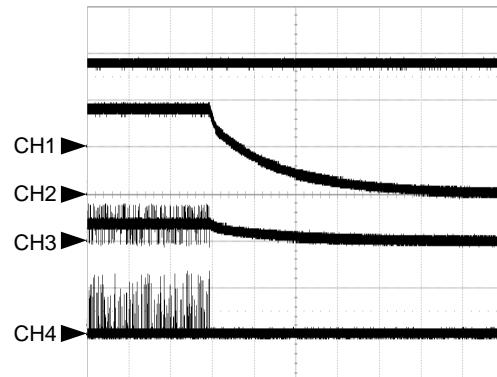
Operating Waveforms

Power on EN



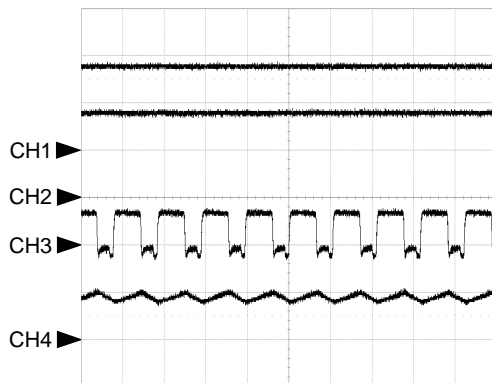
CH1: V_{IN} -2V/div
 CH2: V_{OUT} -1V/div
 CH3: SW-5V/div
 CH4: I_L -500mA/div
 Time: 100us/div

Power off EN



CH1: V_{IN} -2V/div
 CH2: V_{OUT} -1V/div
 CH3: SW-5V/div
 CH4: I_L -500mA/div
 Time: 1s/div

Normal Operation

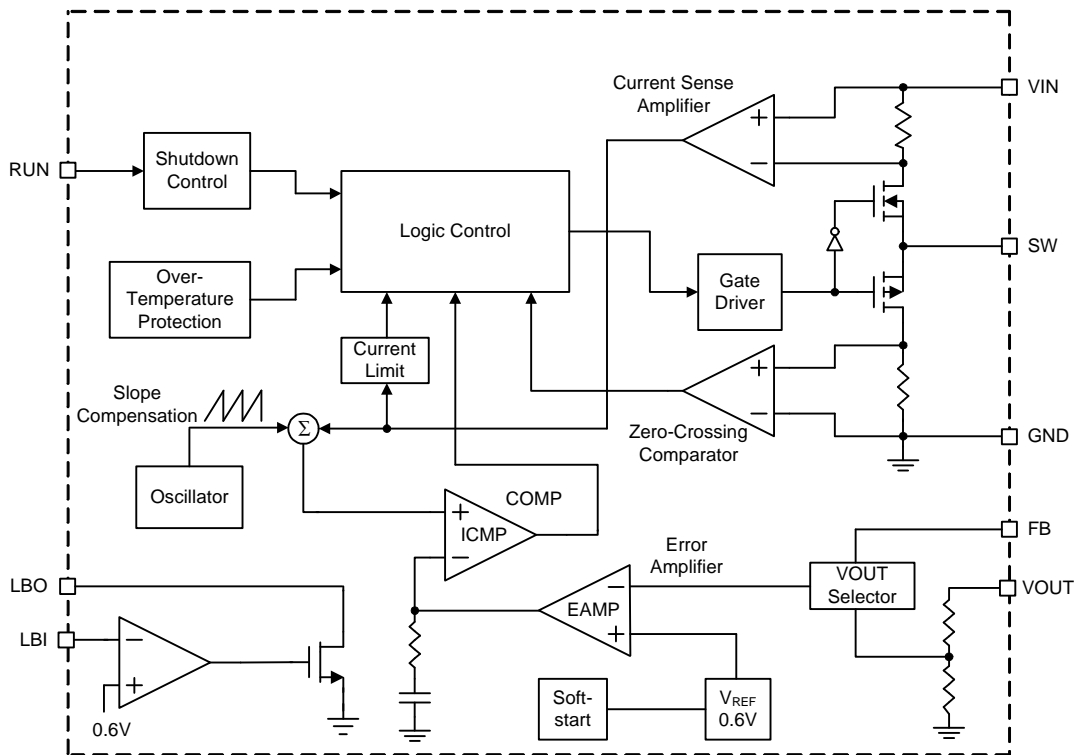


CH1: V_{IN} -2V/div
 CH2: V_{OUT} -1V/div
 CH3: SW-5V/div
 CH4: I_L -1A/div
 Time: 500ns/div

Pin Description

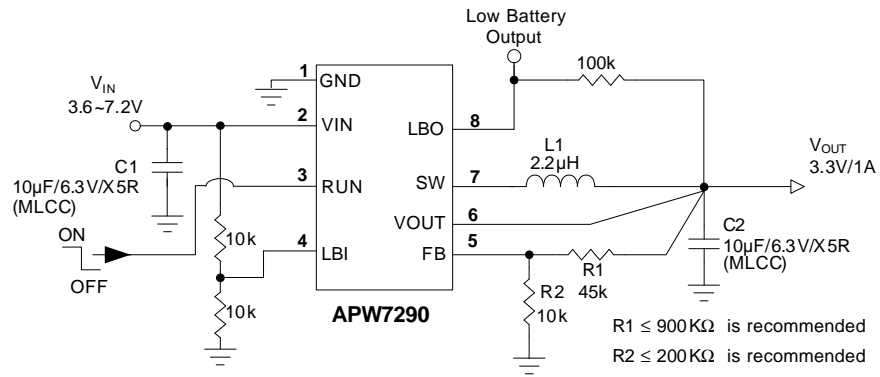
PIN		Function
NO.	NAME	
1	GND	Power and Signal Ground.
2	VIN	Device and Converter Supply Pin. Must be closely decoupled to GND with a 4.7 μ F or greater ceramic capacitor.
3	RUN	Enable Control Input. Forcing this pin above 1.0V enables the device. Forcing this pin below 0.4V shuts it down. In shutdown, all functions are disabled to decrease the supply current below 0.5 μ A. Do not leave RUN pin floating.
4	LBI	Low-battery comparator input. Internally set to trip at 0.6V.
5	FB	Feedback Input Pin and output voltage select Pin. The buck regulator senses feedback voltage via FB and regulates the FB voltage at 0.6V. Connecting FB with a resistor-divider from the output sets the output voltage of the buck converter. If FB connects to GND, VOUT is fixed 1.8V.
6	VOUT	Output Voltage. Output voltage feedback input if FB pin is connected to VOUT or GND.
7	SW	Switch Node Connected to Inductor. This pin connects to the drains of the internal main and synchronous power MOSFETs switches.
8	LBO	Open-drain low battery comparator output. Connect LBO to OUT through a 100k Ω resistor. LBO is low as $V_{LBI} < 0.6V$. Open-drain device is turned off during shutdown.

Block Diagram

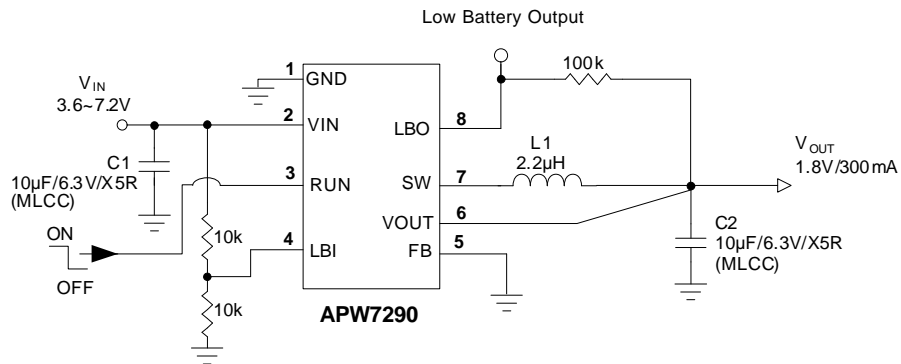


Typical Application Circuit

Toy Application



E-Book Application



Power Sequence: a. VIN Rise up -> RUN Rise up b. RUN Rise up -> VIN Rise up

Function Description

Main Control Loop

The APW7290 is a constant frequency, synchronous rectifier and current-mode switching regulator. In normal operation, the internal P-channel power MOSFET is turned on each cycle. The peak inductor current at which ICMP turn off the P-FET is controlled by the voltage on the COMP node, which is the output of the error amplifier (EAMP). An external resistive divider connected between VOUT and ground allows the EAMP to receive an output feedback voltage VFB at FB pin. When the load current increases, it causes a slightly decrease in VFB relative to the 0.6V reference, which in turn causes the COMP voltage to increase until the average inductor current matches the new load current.

Under-Voltage Lockout

An under-voltage lockout function prevents the device from operating if the input voltage on VIN is lower than approximately 3V (Typ.). The device automatically enters the shutdown mode if the voltage on VIN drops below approximately 3V. This under-voltage lockout function is implemented in order to prevent the malfunctioning of the converter.

Soft-Start

The APW7290 has a built-in soft-start to control the output voltage rise during start-up. During soft-start, an internal ramp voltage, connected to the one of the positive inputs of the error amplifier, raises up to replace the reference voltage (0.6V typical) until the ramp voltage reaches the reference voltage. Then the voltage on FB regulated at reference voltage.

Enable/Shutdown

Driving RUN to ground places the APW7290 in shutdown mode. When in shutdown, the internal power MOSFETs turn off, all internal circuitry shuts down and the quiescent supply current reduces to 0.5 μ A maximum.

Pulse Frequency Modulation Mode (PFM)

The APW7290 is a fixed frequency, peak current mode PWM step-down converter. At light loads, the APW7290 will automatically enter in pulse frequency mode opera-

tion to reduce the dominant switching losses. In PFM operation, the inductor current may reach zero or reverse on each pulse. A zero current comparator turn off the N-FET, forcing DCM operation at light load. These controls get very low quiescent current, help to maintain high efficiency over the complete load range.

Slope Compensation and Inductor Peak Current

Slope compensation provides stability in constant frequency architectures by preventing sub-harmonic oscillations at high duty cycles. It is accomplished internally by adding a compensating ramp to the inductor current signal at duty cycles in excess of 40%. Normally, the result is in a reduction of maximum inductor peak current for duty cycles > 40%. However, the APW7290 uses a special scheme that counteracts this compensating ramp, which allows the maximum inductor peak current to remain unaffected throughout all duty cycles.

Adaptive Shoot-Through Protection

The gate driver incorporates adaptive shoot-through protection to high-side and low-side MOSFETs from conducting simultaneously and shorting the input supply. This is accomplished by ensuring the falling gate has turned off one MOSFET before the other is allowed to rise.

During turn-off the low-side MOSFET, the internal LGATE voltage is monitored until it below 1.5V threshold, at which time the UGATE is released to rise after a constant delay. During turn-off the high-side MOSFET, the UGATE voltage is also monitored until it above 1.5V threshold, at which time the LGATE is released to rise after a constant delay.

Dropout Operation

As the input supply voltage decreases to a value approaching the output voltage, the duty cycle increases toward the maximum on time. Further reduction of the supply voltage forces the main switch to remain on for more than one cycle until it reaches 100% duty cycle. The output voltage will then be determined by the input voltage minus the voltage drop across the P-FET and the inductor.

Function Description (Cont.)

Dropout Operation (Cont.)

An important detail to remember is that on resistance of P-FET switch will increase at low input supply voltage. Therefore, the user should calculate the power dissipation when the APW7290 is used at 100% duty cycle with low input voltage.

Over-Temperature Protection (OTP)

The over-temperature circuit limits the junction temperature of the APW7290. When the junction temperature exceeds 150°C, a thermal sensor turns off the both power MOSFETs, allowing the devices to cool. The thermal sensor allows the converters to start a soft-start process and regulate the output voltage again after the junction temperature cools by 30°C. The OTP designed with a 30°C hysteresis lowers the average Junction Temperature (T_j) during continuous thermal overload conditions, increasing the life time of the device.

Short-Circuit Protection

When the output is shorted to ground, the frequency of the oscillator is reduced to about 210 kHz, 1/7 of the nominal frequency. This frequency fold back ensures that the inductor current has more time to decay, thereby preventing runaway. The oscillator's frequency will progressively increase to 1.5MHz when V_{FB} or V_{OUT} rises above 0V.

Low Battery Detection

The low battery detection is used to monitor the battery voltage and to generate a signal. This function includes two pins, LBI is the inverting input of the comparator and LBO is an open drain output (See Block Diagram). When the LBI voltage drops below the threshold voltage 0.6V, the open drain device will turn on and LBO becomes low. The Low battery threshold voltage can be programmed with a resistive divider from battery to LBI pin to the ground. Since the LBO is an open drain output, it usually requires an external pull-up resistor.

Application Information

Input Capacitor Selection

Because buck converters have a pulsating input current, a low ESR input capacitor is required. This results in the best input voltage filtering, minimizing the interference with other circuits caused by high input voltage spikes. Also, the input capacitor must be sufficiently large to stabilize the input voltage during heavy load transients. For good input voltage filtering, usually a 4.7μF input capacitor is sufficient. It can be increased without any limit for better input-voltage filtering. Ceramic capacitors show better performance because of the low ESR value, and they are less sensitive against voltage transients and spikes compared to tantalum capacitors. Place the input capacitor as close as possible to the input and GND pin of the device for better performance.

Inductor Selection

For high efficiencies, the inductor should have a low DC resistance to minimize conduction losses. Especially at high-switching frequencies, the core material has a higher impact on efficiency. When using small chip inductors, the efficiency is reduced mainly due to higher inductor core losses. This needs to be considered when selecting the appropriate inductor. The inductor value determines the inductor ripple current. The larger the inductor value, the smaller the inductor ripple current and the lower the conduction losses of the converter. Conversely, larger inductor values cause a slower load transient response. A reasonable starting point for setting ripple current, ΔI_L is 40% of maximum output current. The recommended inductor value can be calculated as below:

$$L \geq \frac{V_{OUT} \left(1 - \frac{V_{OUT}}{V_{IN}}\right)}{F_{SW} \cdot \Delta I_L}$$

$$I_{L(MAX)} = I_{OUT(MAX)} + 1/2 \times \Delta I_L$$

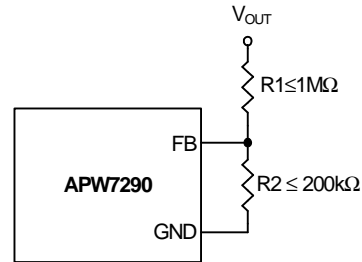
To avoid the saturation of the inductor, the inductor should be rated at least for the maximum output current of the converter plus the inductor ripple current.

Output Voltage Setting

In the adjustable version, the output voltage is set by a resistive divider. The external resistive divider is connected to the output, allowing remote voltage sensing as

shown in “Typical Application Circuits”. A suggestion of maximum value of R2 is 200kΩ to keep the minimum current that provides enough noise rejection ability through the resistor divider. The output voltage can be calculated as below:

$$V_{OUT} = V_{REF} \cdot \left(1 + \frac{R1}{R2}\right) = 0.6 \cdot \left(1 + \frac{R1}{R2}\right)$$

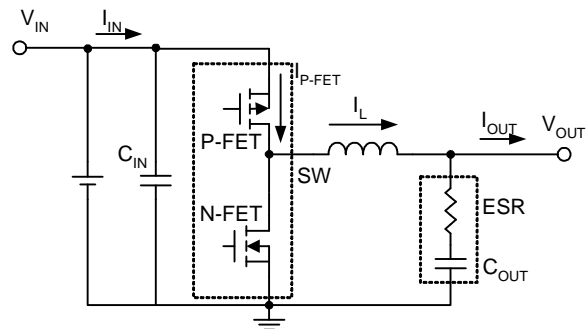


Output Capacitor Selection

The current-mode control scheme of the APW7290 allows the use of tiny ceramic capacitors. The higher capacitor value provides the good load transients response. Ceramic capacitors with low ESR values have the lowest output voltage ripple and are recommended. If required, tantalum capacitors may be used as well. The output ripple is the sum of the voltages across the ESR and the ideal output capacitor.

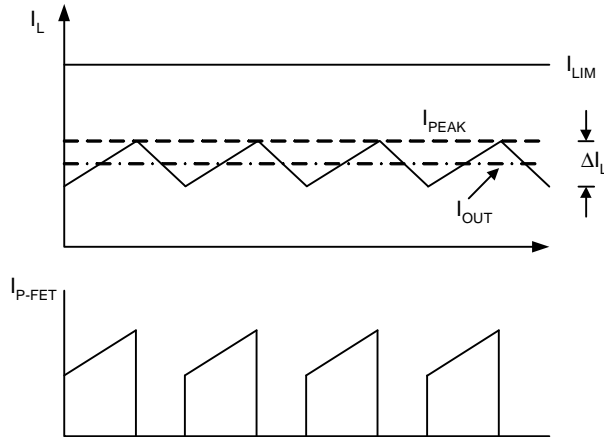
$$\Delta V_{OUT} \cong \frac{V_{OUT} \cdot \left(1 - \frac{V_{OUT}}{V_{IN}}\right)}{F_{SW} \cdot L} \cdot \left(ESR + \frac{1}{8 \cdot F_{SW} \cdot C_{OUT}}\right)$$

When choosing the input and output ceramic capacitors, choose the X5R or X7R dielectric formulations. These dielectrics have the best temperature and voltage characteristics of all the ceramics for a given value and size.

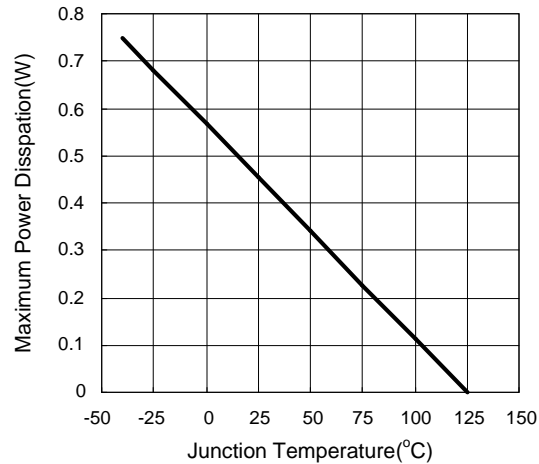


Application Information (Cont.)

Output Capacitor Selection (Cont.)



The maximum power dissipation on the device can be shown as follow figure:



Thermal Consideration

In most applications, the APW7290 does not dissipate much heat due to its high efficiency. But, in applications where the APW7290 is running at high ambient temperature with low supply voltage and high duty cycles, the heat dissipated may exceed the maximum junction temperature of the part. If the junction temperature reaches approximately 150°C, both power switches will be turned off and the SW node will become high impedance.

To avoid the APW7290 from exceeding the maximum junction temperature, the user will need to do some thermal analysis. The goal of the thermal analysis is to determine whether the power dissipated exceeds the maximum junction temperature of the part. The power dissipated by the part is approximated:

$$P_D \cong I_{OUT}^2 \times (R_{P-FET} \times D + R_{N-FET} \times (1-D))$$

The temperature rise is given by:

$$T_R = (P_D)(\theta_{JA})$$

Where P_D is the power dissipated by the regulator, D is duty cycle of main switch

$$D = V_{OUT}/V_{IN}$$

The θ_{JA} is the thermal resistance from the junction of the die to the ambient temperature. The junction temperature, T_J , is given by:

$$T_J = T_A + T_R$$

Where T_A is the ambient temperature.

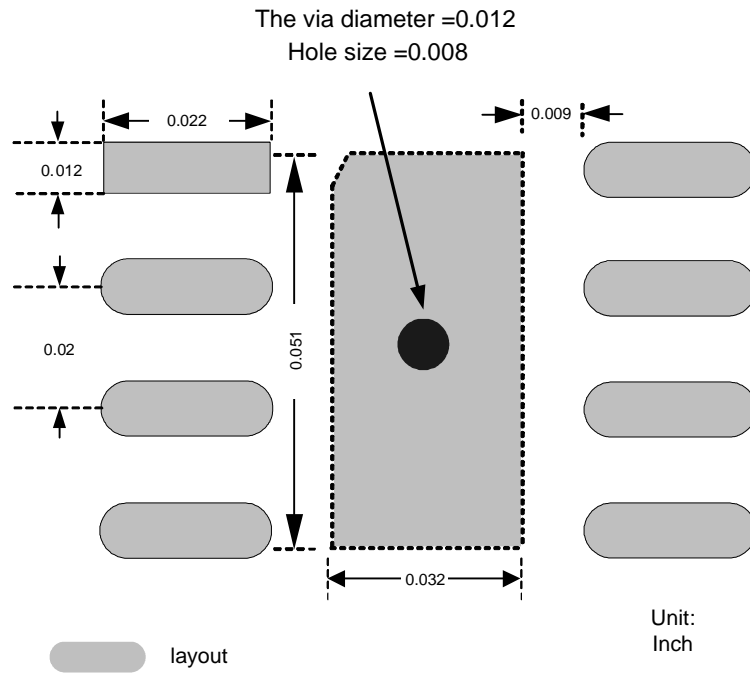
Layout Consideration

For all switching power supplies, the layout is an important step in the design; especially at high peak currents and switching frequencies. If the layout is not carefully done, the regulator might show noise problems and duty cycle jitter.

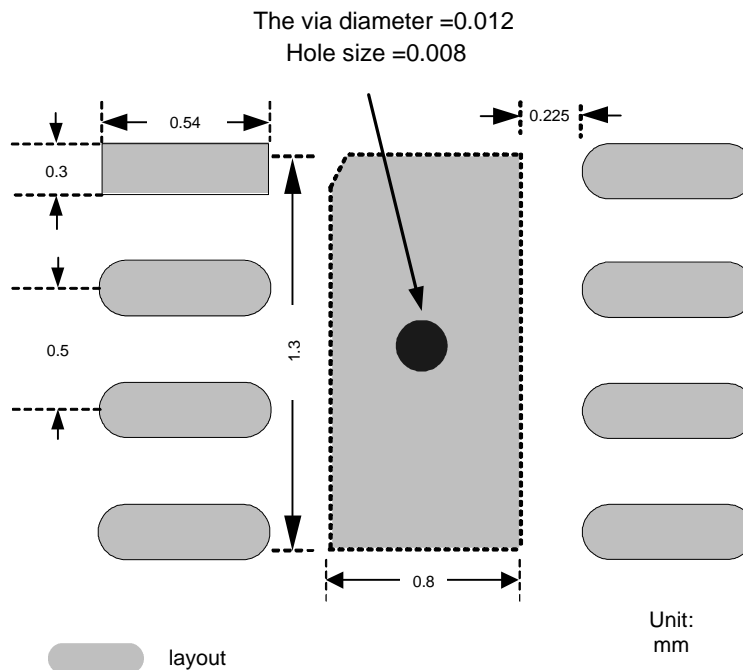
1. The input capacitor should be placed close to the VIN and GND. Connecting the capacitor and VIN/GND with short and wide trace without any via holes for good input voltage filtering. The distance between VIN/GND to capacitor less than 2mm respectively is recommended.
2. To minimize copper trace connections that can inject noise into the system, the inductor should be placed as close as possible to the SW pin to minimize the noise coupling into other circuits.
3. The output capacitor should be place closed to converter VOUT and GND.
4. Since the feedback pin and network is a high impedance circuit the feedback network should be routed away from the inductor. The feedback pin and feedback network should be shielded with a ground plane or trace to minimize noise coupling into this circuit.
5. A star ground connection or ground plane minimizes ground shifts and noise is recommended.

Application Information (Cont.)

Recommended Minimum Footprint



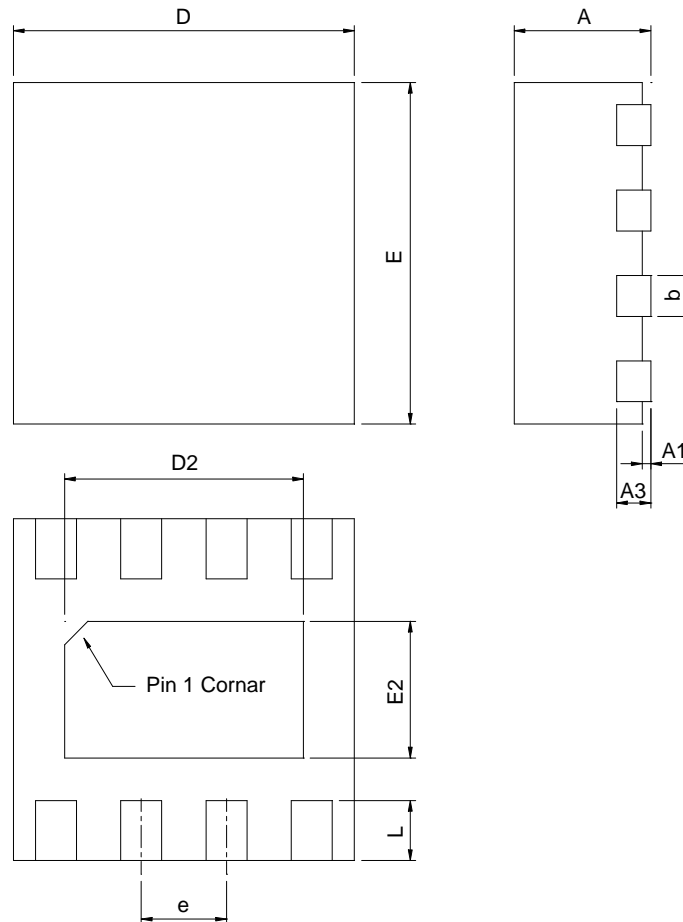
layout



layout

Package Information

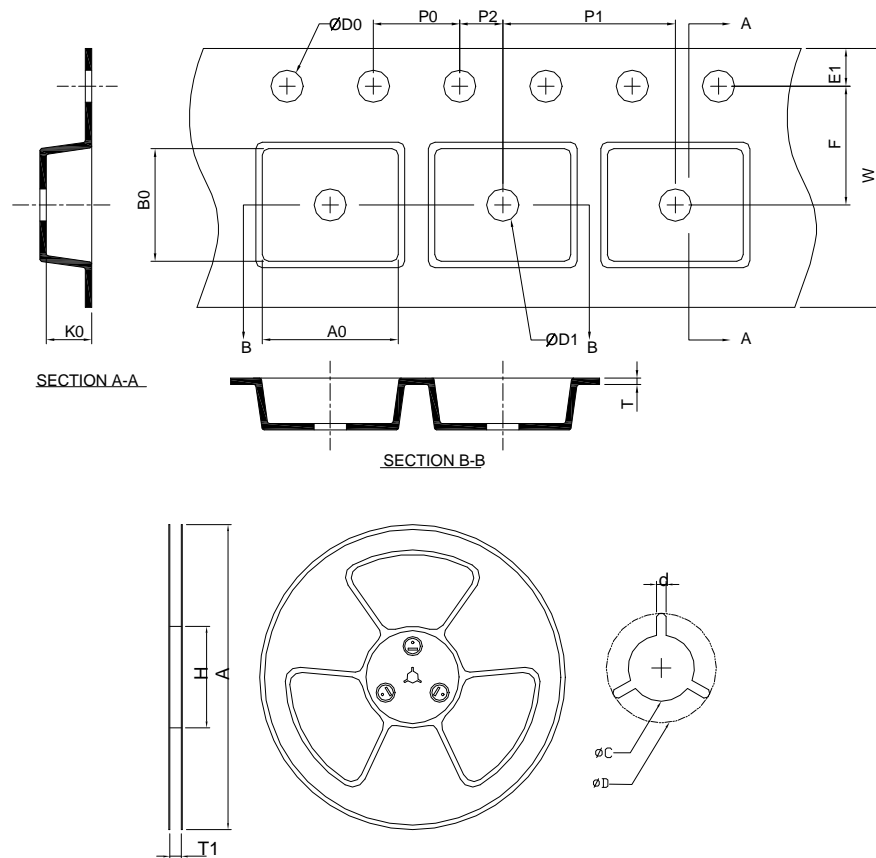
TDFN2x2-8



SYMBOL	TDFN2x2-8			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.70	0.80	0.028	0.031
A1	0.00	0.05	0.000	0.002
A3	0.20 REF		0.008 REF	
b	0.18	0.30	0.007	0.012
D	1.90	2.10	0.075	0.083
D2	1.00	1.60	0.039	0.063
E	1.90	2.10	0.075	0.083
E2	0.60	1.00	0.024	0.039
e	0.50 BSC		0.020 BSC	
L	0.30	0.45	0.012	0.018

Note : 1. Followed from JEDEC MO-229 WCCD-3.

Carrier Tape & Reel Dimensions



Application	A	H	T1	C	d	D	W	E1	F
TDFN2x2-8	178.0 ±0.00	50 MIN.	8.4+2.00 -0.00	13.0+0.50 -0.20	1.5 MIN.	20.2 MIN.	8.0 ±0.20	1.75 ±0.10	3.50 ±0.05
	P0	P1	P2	D0	D1	T	A0	B0	K0
	4.0 ±0.10	4.0 ±0.10	2.0 ±0.05	1.5+0.10 -0.00	1.5 MIN.	0.6+0.00 -0.4	3.35 MIN	3.35 MIN	1.30 ±0.20

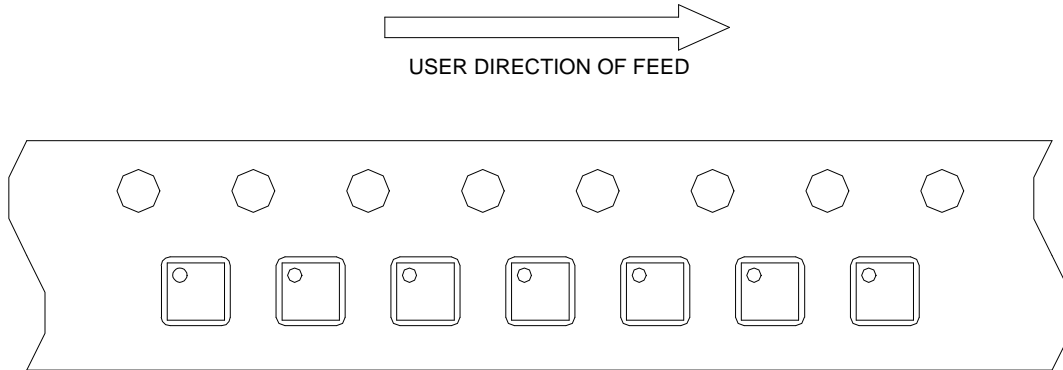
(mm)

Devices Per Unit

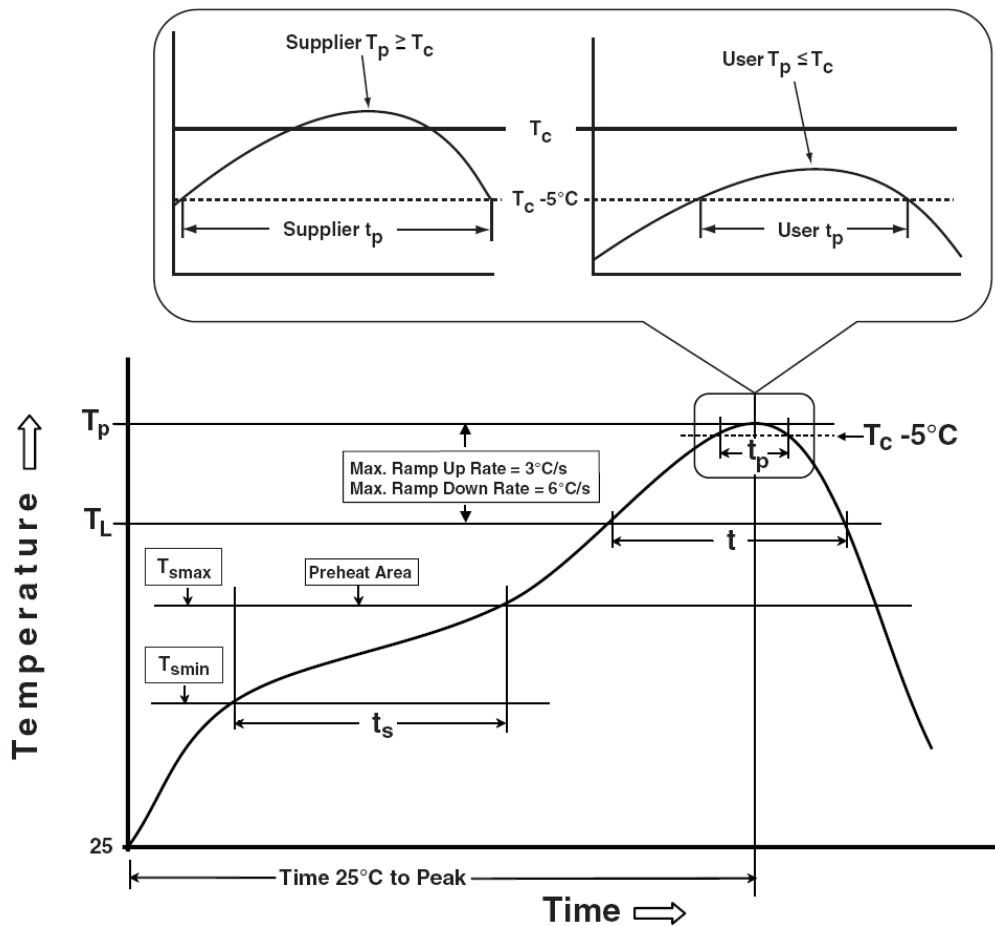
Package Type	Unit	Quantity
TDFN2x2-8	Tape & Reel	3000

Taping Direction Information

TDFN2x2-8



Classification Profile



Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat & Soak		
Temperature min (T_{smin})	100 °C	150 °C
Temperature max (T_{smax})	150 °C	200 °C
Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds	60-120 seconds
Average ramp-up rate (T_{smax} to T_p)	3 °C/second max.	3 °C/second max.
Liquidous temperature (T_L)	183 °C	217 °C
Time at liquidous (t_L)	60-150 seconds	60-150 seconds
Peak package body Temperature (T_p)*	See Classification Temp in table 1	See Classification Temp in table 2
Time (t_p)** within 5°C of the specified classification temperature (T_c)	20** seconds	30** seconds
Average ramp-down rate (T_p to T_{smax})	6 °C/second max.	6 °C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.
* Tolerance for peak profile Temperature (T_p) is defined as a supplier minimum and a user maximum.		
** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.		

Table 1. SnPb Eutectic Process – Classification Temperatures (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

Reliability Test Program

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HOLT	JESD-22, A108	1000 Hrs, Bias @ $T_j=125^\circ\text{C}$
PCT	JESD-22, A102	168 Hrs, 100%RH, 2atm, 121°C
TCT	JESD-22, A104	500 Cycles, -65°C~150°C
HBM	MIL-STD-883-3015.7	VHBM 2KV
MM	JESD-22, A115	VMM 200V
Latch-Up	JESD 78	10ms, 1 _{tr} 100mA

Customer Service

Anpec Electronics Corp.

Head Office :

No.6, Dusing 1st Road, SBIP,

Hsin-Chu, Taiwan, R.O.C.

Tel : 886-3-5642000

Fax : 886-3-5642050

Taipei Branch :

2F, No. 11, Lane 218, Sec 2 Jhongsing Rd.,

Sindian City, Taipei County 23146, Taiwan

Tel : 886-2-2910-3838

Fax : 886-2-2917-3838